ASSOCIATION CONNECTING ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® international and Pai	PC. Bannockl	burn, Illinois, A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declaration entities the declaration entities and the declaration entities and the declaration entities and the declaration entities are also been as the declaration entities are also been	on of the su compasses	bstances v all lower	vithin the manufactu level materials for v	urer listed which the	item. Note: nanufacture	if the item is an as er has engineering	sembly with low responsibility.	
				Form Type Distribute					rials and Mfg Information					
upplier Information														
Company name* Com			Company unique ID			Unique ID Authority				Respon	Response Date*			
nsemi										2024-0	2024-05-09			
ontact Name Title - Contact			act			Phone - Contact*				Email ·	Email - Contact*			
Product-Env-Stewards Product En			Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Rep			presentative			Phone - Representative*				Email ·	Email - Representative*			
Product-Env-Stewards Produc			oduct Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Date	Version	М	Manufacturing Site		Weight*	UOM	Unit Type	
	NC7SP3	NC7SP32P5X ULP		ULP 2-Input OR Gate		2024-05-09		C	CNS		5.842	mg	Each	
Anufacturing Proccess Informa	tion													
Terminal Plating / Grid Array M	aterial 7	Ferminal Base	Alloy J-STD-020 MSL Ra		L Rating	Peak Proce	ocess Body Temperatu		ure Max Time at Peak Tempera		ture Num	ber of Reflow Cyc	eles	
Matte Tin (Sn) - annealed CU Allo		CU Alloy	1			260 C		30 seco		seconds 3				
omments														
vel 1 - maximum time at peak temperatu	ure during so	Idering is 10-3	0 seconds											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chror	oHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl hthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.147	mg	Supplier	Silicon (Si)	7440-21-3		0.147	mg
Die Attach Epoxy	0.04	mg	Supplier	Silver (Ag)	7440-22-4		0.0368	mg
			Supplier	Phenolic Resin-2	54208-63-8		0.0032	mg
Lead Frame	2.213	mg	Supplier	Silver (Ag)	7440-22-4		0.0066	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0027	mg
			Supplier	Iron (Fe)	7439-89-6		0.052	mg
			Supplier	Copper (Cu)	7440-50-8		2.151	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0007	mg
Mold Compound-Black	3.182	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.9228	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0318	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		2.2274	mg
Plating	0.23	mg	Supplier	Tin (Sn)	7440-31-5		0.23	mg
Wire Bond - Au	0.03	mg	Supplier	Gold (Au)	7440-57-5		0.03	mg